

bq27520EVM With System-Side, Single-Cell Impedance Track™ Technology

This evaluation module (EVM) is a complete evaluation system for the bq27520. The EVM includes one bq27520 circuit module, a current sense resistor, and one thermistor. An EV2300 board is required to interface this EVM with the PC and can be purchased separately. The circuit module includes one bq27520 integrated circuit and all other onboard components necessary to monitor and predict capacity for a system-side fuel gauge solution. The circuit module connects directly across the battery pack. With the EV2300 interface board and software, the user can read the bq27520 data registers, program the chipset for different pack configurations, log cycling data for further evaluation, and evaluate the overall functionality of the bq27520 solution under different charge and discharge conditions. The latest Microsoft® Windows® based PC software can be downloaded from the product folder on the Texas Instruments Web site.

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Features www.ti.com

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1 Features

- Complete evaluation system for the bq27520 gas gauge with Impedance Track technology
- Populated circuit module for quick setup
- · Personal computer (PC) software and interface board for easy evaluation
- · Software that allows data logging for system analysis
- Ability to upgrade to the latest firmware version by flash reprogramming

1.1 Kit Contents

- bq27520 circuit module (HPA568)
- NTC103AT thermistor

This EVM is used for the evaluation of different bq27520-based products. Ensure that you visit the product Web folder at www.ti.com to download the latest firmware version, evaluation software, and documentation for the associated product to be evaluated.

1.2 Ordering Information

Table 1. Ordering Information

EVM PART NUMBER	CHEMISTRY	CONFIGURATION	CAPACITY
bq27520EVM	Li-ion	1 cell	Any

2 bq27520-Based Circuit Module

The bq27520-based circuit module is a complete and compact example solution of a bq27520 circuit for battery management. The circuit module incorporates a bq27520 battery gas gauge integrated circuit (IC) and all other components necessary to accurately predict the capacity of 1-series Li-ion cell.

2.1 Circuit Module Connections

Contacts on the circuit module provide the following connections:

- Direct connection to the battery pack (J2 or J3): PACK+, PACK-, and TS
- To the serial communications port (J8): SDA, SCL, and VSS
- The system load and charger connect across charger and load (J6 and J7): CHARGER-/LOAD- and CHARGER+/LOAD+.
- Access to signal outputs (J5): SOC_INT, BAT_GD, and BAT_LOW

2.2 Pin Descriptions

PIN NAME	DESCRIPTION
PACK+	Pack positive terminal
PACK-	Pack negative terminal
TS	Pack thermistor input that leads to IC TS pin
SDA	I ² C communication data line
SCL	I ² C communication clock line
VSS	Signal return for communication line, shared with charger and ground



PIN NAME	DESCRIPTION
CHG+/LOAD+	High potential of load or charger connection
CHG-/LOAD-	Low potential of load or charger connection (system VSS)
BAT_GD	Access to push-pull output that indicates that pack is ready to be connected to system
BAT_LOW	Access to push-pull output that signals low State-of-Charge (SOC)
SOC_INT	Access to open-drain output that signals interrupt for changes in SOC

3 Circuit Module Physical Layouts, Bill of Materials, and Schematic

This section contains the board layout, bill of materials, assembly drawings, and schematic for the bq27520 circuit module.

3.1 Board Layout

This section shows the printed-circuit board (PCB) layers (Figure 1 through Figure 4), assembly drawing, and schematic for the bq27520 module.

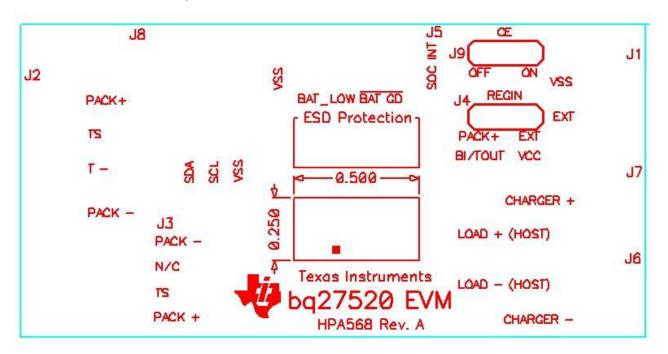


Figure 1. bq27520EVM-001 Layout - Silk Screen



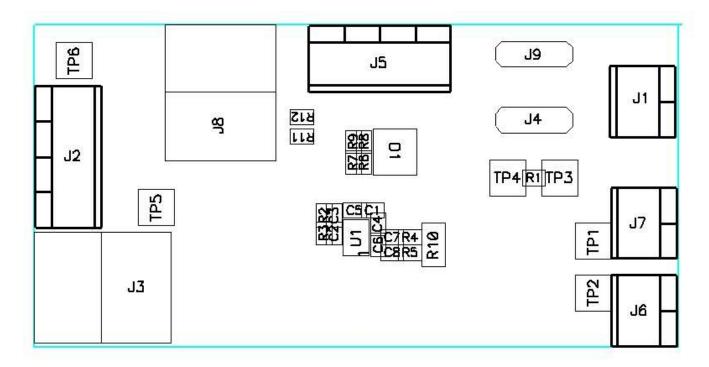


Figure 2. Top Assembly

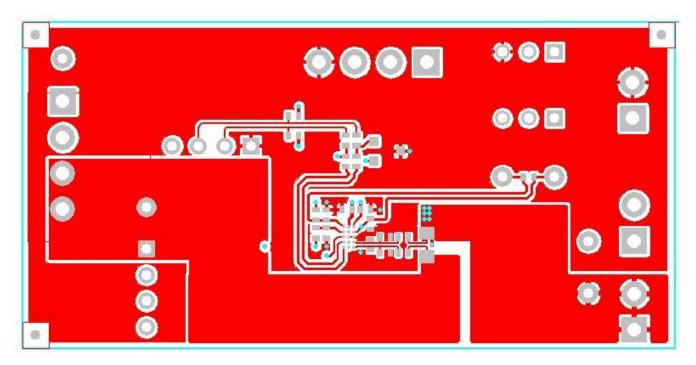


Figure 3. Top Layer



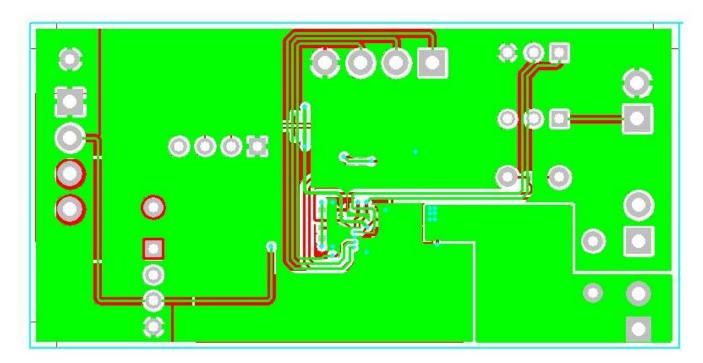


Figure 4. Bottom Layer

3.2 Bill of Materials and Schematic

Table 2. Bill of Materials

Count	Ref Des	Description	Size	MFG	Part Number
6	C1, C2, C5–C8	Capacitor, Ceramic, 0.1 μF, 10 V, X5R	0402	Murata	GRM155R61A104KA01D
1	C3	Capacitor, Ceramic, 33 nF, 10 V, X7R, +/-10%	0402	Murata	GRM155R71A333KA01D
1	C4	Capacitor, Ceramic, 1 µF, 6.3V, X5R	0402	Murata	GRM155R60J105KE19D
1	D1	Diode, Dual, Zener, 5.6 V, 300 mW	SOT23	Diodes	AZ23C5V6-7
3	J1, J6, J7	Terminal Block, 2-pin, 6 A, 3.5 mm	0.27 x 0.25 inch	OST	ED555/2DS
2	J2, J5	Terminal Block, 4-pin, 6 A, 3.5 mm	0.55 x 0.25 inch	OST	ED555/4DS
2	J3, J8	Header, Friction Lock Assy, 4-pin Right Angle,	0.400 x 0.500	Molex	22-05-3041
2	J4, J9	Header, Male 3-pin, 100-mil spacing, (36-pin strip)	0.100 inch x 3	Sullins	PEC36SAAN
1	R1	Resistor, Chip, 1.80 MΩ, 1/16 W, 5%	0402	Std	Std
1	R10	Resistor, Chip, 0.01 Ω, 1/4 W, 1%	0805	Vishay	WSL0805R0100FEA18
2	R11, R12	Resistor, Chip, 10 kΩ, 1/16 W, 5%	0402	Std	Std
1	R2	Resistor, Chip, 18.2 kΩ, 1/16 W, 5%	0402	Std	Std
1	R3	Resistor, Chip, 1 kΩ, 1/16 W, 5%	0402	Std	Std
6	R4-R9	Resistor, Chip, 100 Ω, 1/16 W, 5%	0402	Std	Std
3	TP1, TP3, TP6	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	Keystone	5000
2	TP2, TP5	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	Keystone	5001
1	TP4	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	Keystone	5002
1	U1	IC, System-Side Impedance-Track Fuel Gauge	BGA	Texas Instruments	BQ27520YZF



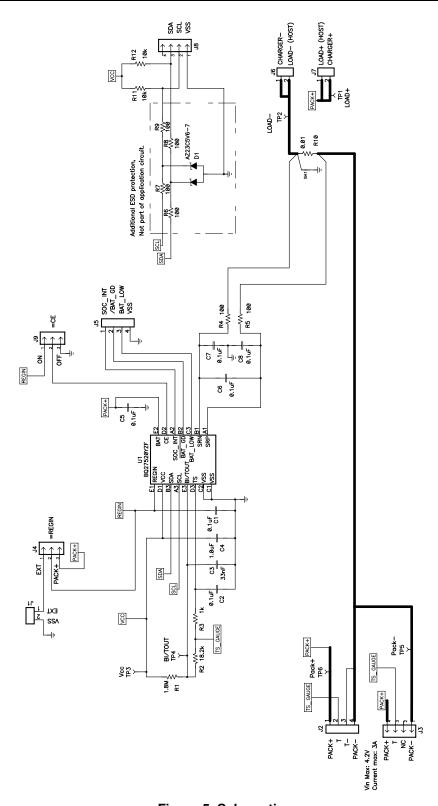


Figure 5. Schematic



3.3 bq27520 Circuit Module Performance Specification Summary

This section summarizes the performance specifications of the bq27520 circuit module.

Table 3. Performance Specification Summary

Specification	Min	Тур	Max	Units
Input voltage Pack+ to Pack-	2.7	3.6	4.3	V
Charge and discharge current	0	1	2	Α

4 EVM Hardware and Software Setup

This section describes how to install the bq27520EVM PC software and how to connect the different components of the EVM.

4.1 Software Installation

Find the latest software version at http://www.ti.com/tool/bqStudio. Use the following steps to install Battery Management Studio:

- 1. Ensure that the EV2300 is not connected to the PC through a USB cable before starting this procedure.
- 2. Select the Tool and Software tab in the product folder.
- 3. Under the Software section, click on Battery Management Studio (bgStudio) Software Suite.
- 4. Click the **Download** button to download the software.
- 5. Download software to hard drive.
- 6. Double-click the software executable and follow all instructions and prompts.

5 Troubleshooting Unexpected Dialog Boxes

The user that is downloading the files must be logged in as the administrator.

The driver is not signed, so the administrator must allow installation of unsigned drivers in the operating system policy.



Hardware Connection www.ti.com

6 Hardware Connection

The bq27520EVM-001 comprises three hardware components: the bq27520 circuit module, the EV2300 PC interface board, and the PC.

6.1 Connecting the bq27520 Circuit Module to a Battery Pack

Figure 6 shows how to connect the bq27520 circuit module to the cells and system load/charger.

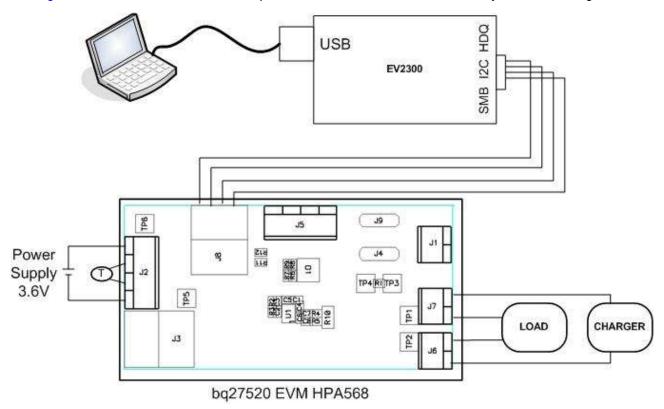


Figure 6. bq27520 Circuit Module Connection to Cell and System Load/Charger

6.2 PC Interface Connection

The following steps configure the hardware for interface to the PC.

1. Connect the bq27520-based EVM to the EV2300 using wire leads as shown in Table 4.

bq27520-Based Battery EV2300
SDA SDA

SCL

GND

Table 4. Circuit Module to EV2300 Connections

2. Connect the PC USB cable to the EV2300 and the PC USB port.

The bg27520EVM-001 is now set up for operation.

SCL

VSS



www.ti.com Operation

7 Operation

This section details the operation of the bqStudio software.

7.1 Starting the Program

Run bqStudio from the Start | All Programs | Texas Instruments | Battery Management Studio. The main screen (Figure 7) appears. If instead of Figure 7 appearing, Figure 8 appears, it may mean that the EVM is not connected to the computer correctly. Make sure that the USB interface (EV2300 or EV2400 or GDK) and the bq27520 are connected and restart bqStudio. If this still does not resolve the issue, check if the I²C pull-up resistors are connected. Data begins to appear once the <Refresh> (single-time scan) button is clicked, or when the Scan button is clicked. To disable the scan feature, simply click the **Scan** button again.

The continuous scanning period can be set by opening Window | Preferences \rightarrow Registers section. The range for this interval is 0 ms to 65,535 ms. Only items that are selected for scanning are scanned within this period.

Battery Management Studio provides a logging function which logs the values that were last scanned. To enable this function, select the Start Log button; this causes the Scan button to be pressed. When logging is Stopped, the Scan button will still be selected and has to be manually clicked again.

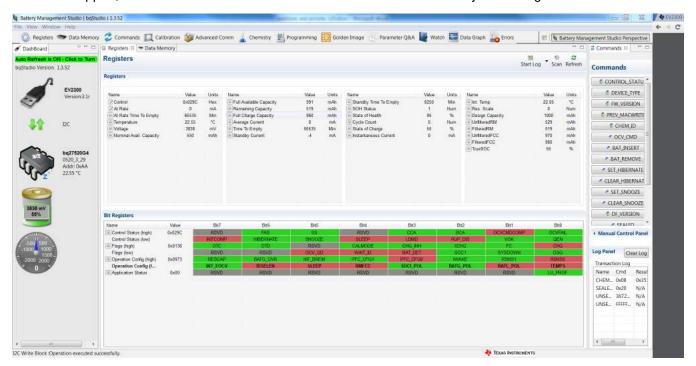


Figure 7. Registers Screen

This screen (Figure 7) shows the RAM data in the bq27520 device. Additional *Flags* and *Status* data can be viewed at the bottom of the *Registers* screen.



Operation www.ti.com

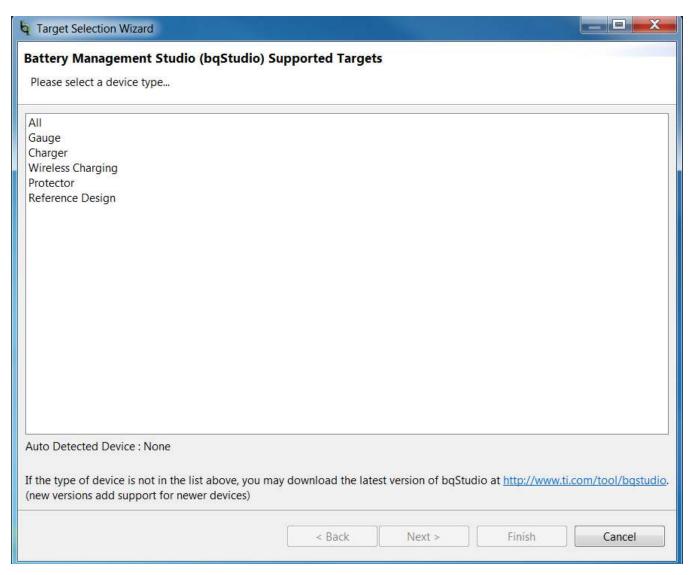


Figure 8. bqStudio Default Page

7.2 Setting Programmable bq27520 Options

The bq27520 data memory comes configured per the default settings detailed in the bq27520 technical reference manual (SLUUA35). Ensure that the settings are correctly changed to match the pack and application for the bq27520 solution being evaluated.

IMPORTANT: The correct setting of these options is essential to get the best performance.

The settings can be configured using the *Data Memory* screen (Figure 9).



www.ti.com Operation

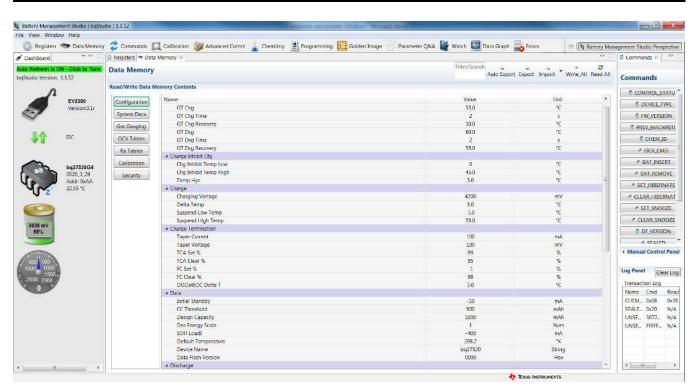


Figure 9. Data Memory Screen

To read all the data from the bq27520 non-volatile flash memory, click on the **Read All** button on the *Data Memory* window. Make sure the device is not sealed and in full access to read or write to the data memory. To update a parameter, click on the desired parameter and a window pops-up that provides details on the selected parameter. Next, enter the value in the value textbox and press **Enter**. After pressing **Enter**, bqStudio updates the selected parameter. The **Import** button in the *Data Memory* window can be clicked in order to import an entire configuration from a specified *.gg.csv file.

Save the configuration to a file by clicking the **Export** button in the *Data Memory* window and entering a file name. The configuration is saved to a *.gg.csv file. The module calibration data is also held in the bq27520 data memory. If the Gauge Dashboard is not displaying any information, then the bq27520 may not be supported by the bqStudio version being used, a bqStudio upgrade may be required.



Calibration www.ti.com

8 Calibration

The bq27520EVM must be calibrated to ensure accurate value reporting. This can be done by going to the *Calibration* window in bqStudio (Figure 10).

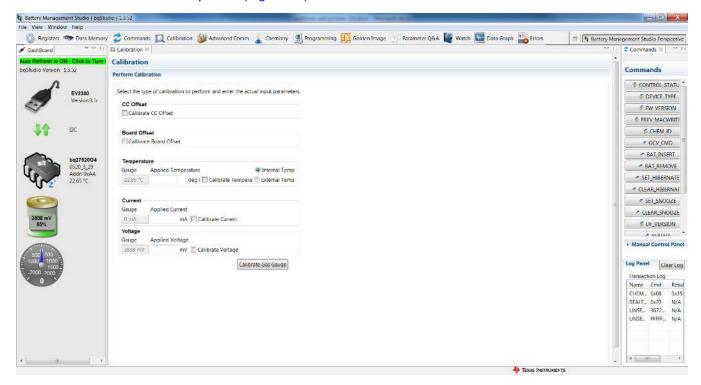


Figure 10. Calibration Window

8.1 Calibrating the bg27520

Calibrate each item one at a time in the order presented in this document. Select the types of calibration to be performed by selecting the corresponding checkbox (see Figure 10).

Enter the measured values for the types selected, if necessary.

Then press the *Calibrate Part as indicated below* button. After all calibration is complete, close the Calibrate subwindow. While the Calibrate subwindow is open, even in the background, the calibration routines are running in firmware. Close the subwindow to ensure that they are stopped before you proceed with configuration or testing.

8.2 CC Offset Calibration

This performs the internal calibration of the coulomb counter input offset. Press the Calibrate Gas Gauge as indicated below button.

8.3 Board Offset Calibration

This performs the offset calibration for the current offset of the board. It is expected that no current is flowing through the sense resistor while performing this calibration step.

- Remove load and short Pack

 to GND.
- Press the Calibration Board Offset button.



www.ti.com Calibration

8.4 Voltage Calibration

Use the following procedures to calibrate voltage:

- Measure the voltage across Pack+ and Pack- with a calibrated meter.
- Type the voltage value in mV into Enter Actual Voltage.
- Measure the temperature for PACK.
- Type the temperature value into Enter Actual Temperature.
- Press the Calibrate Voltage and Temperature as indicated below button.

8.5 Temperature Calibration

- · Measure the temperature for PACK.
- Type the temperature value into Enter Actual Temperature.
- Select if the temperature sensor to calibrate is the internal or external.
- Press the Calibrate Gas Gauge as indicated below button.

8.6 Pack Current Calibration

- Connect a load to LOAD- and LOAD+ that draws approximately 1 A, or connect a current source to LOAD- and Pack-. Ensure that the *Measured Current* reported is negative, or else reverse the connections.
- Measure the current with a calibrated meter, and type the value into Enter Actual Current using (-) for current in discharge direction.
- Press the Calibrate Gas Gauge as indicated below button.



9 Advanced Communication I²C

9.1 I²C Communication

I²C read/write operations are not specific to any gas gauge. These operations serve as general-purpose communication tools (Figure 11).

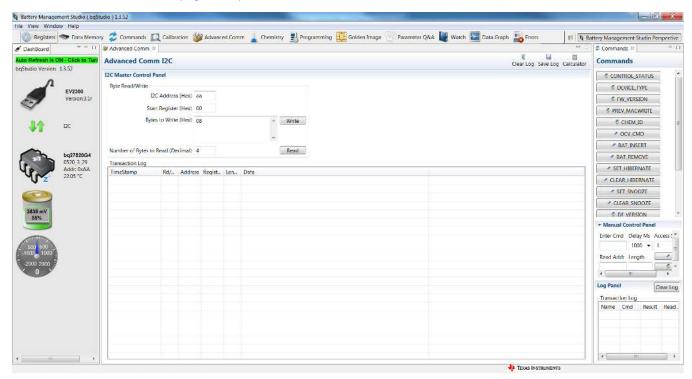


Figure 11. Advanced Communication I²C



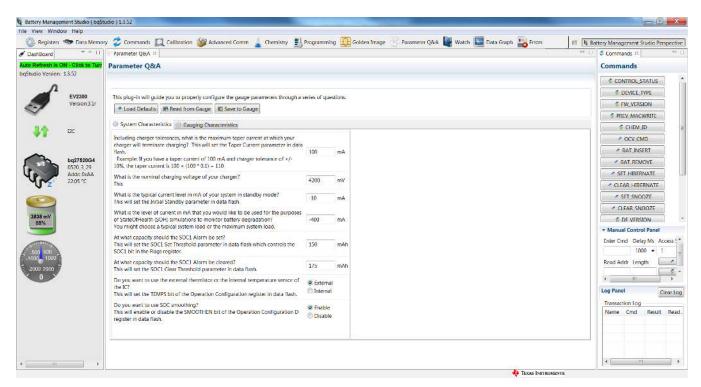


Figure 12. Parameter Q&A Screen



Figure 13. Golden Image Output Screen



Figure 14. Perform Programming Screen



bqStudio™ Software www.ti.com

10 bqStudio™ Software

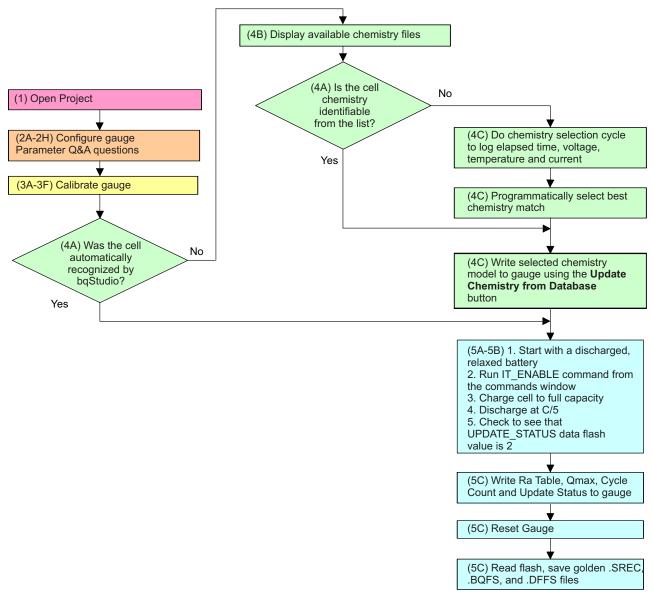
10.1 Introduction

Texas Instruments fuel gauges, employing the Impedance Track algorithm, offer an unmatched array of features and benefits. Sometimes, however, the wide range of configuration settings can seem challenging to get started with the evaluation process. In addition, determining the correct chemistry model and producing the 'golden image' file can be time consuming. The bqStudio program is designed to greatly simplify the process of configuring, calibrating, selecting chemistry, and performing learning cycles through the step-by-step use of a wizard program.

10.2 Program Navigation and Flowchart

The sequence of operation of the bqStudio program can be understood by reviewing the basic flowchart in Figure 15. Using the program is simple – just start a new project and follow the steps sequentially from 1A to 5C. You can use the Next button, or click on the top tabs and left subsection labels to move to any desired page. Some operations must be completed in sequence due to data dependencies, or to implement the proper flow. Therefore, it is recommended that the prescribed sequence be followed, at least at first.





There is not a **Learning Cycle** button in the bq27520EVM bqStudio display.

Figure 15. bqStudio Flowchart

11 Related Documentation From Texas Instruments

To obtain a copy of any of the following TI documents, call the Texas Instruments Literature Response Center at (800) 477-8924 or the Product Information Center (PIC) at (972) 644-5580. When ordering, identify this document by its title and literature number. Updated documents also can be obtained through the TI Web site at www.ti.com.

bq27520, System-Side Impedance Track Fuel Gauge With Integrated LDO data sheet (SLUS955)



Revision History www.ti.com

Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

CI	hanges from A Revision (October 2013) to B Revision	Page
•	Deleted System Requirements and reworded Software Installation sections in EVM Hardware and Software Setup.	7
•	Changed the entire Operation section, text and images.	9
•	Changed Calibrate Screen section to Calibration section, and changed much of the text in the section	12
•	Changed PC Pro Screen section to Advanced Communication PC, changed some text and the images in this section	n 14
•	Changed bqEASY to bqStudio globally in the document. Removed all images and content related to bqEASY	16
•	Changed the Flowchart image.	17
•	Deleted Simplified Configuration Procedures, Files, Completion Checkmarks, and Device Detection sections	17

STANDARD TERMS AND CONDITIONS FOR EVALUATION MODULES

- 1. Delivery: TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, or documentation (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms and conditions set forth herein. Acceptance of the EVM is expressly subject to the following terms and conditions.
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 - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
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 - 2.1 These terms and conditions do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
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- 3 Regulatory Notices:
 - 3.1 United States
 - 3.1.1 Notice applicable to EVMs not FCC-Approved:

This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

3.1.2 For EVMs annotated as FCC - FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:

CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- · Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- · Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur

3.3 Japan

- 3.3.1 Notice for EVMs delivered in Japan: Please see http://www.tij.co.jp/lsds/ti_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
 http://www.tij.co.jp/lsds/ti_ja/general/eStore/notice_01.page
- 3.3.2 Notice for Users of EVMs Considered "Radio Frequency Products" in Japan: EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required by Radio Law of Japan to follow the instructions below with respect to EVMs:

- Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
- 2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
- 3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

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